

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客 户 : _____

PRODUCT 产 品 : _____ SAW FILTER _____

MODEL NO 型 号 : _____ HDF110N SMD-21 _____

PREPARED 编 制 : _____ CHECKED 审 核 : _____

APPROVED 批 准 : _____ D A T E 日 期 : _____ 2006-5-11 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子股份有限公司
Shoulder Electronics Limited

更改历史记录

History Record

[illegible]

1. SCOPE

This specification shall cover the characteristics of SAW filter F110N.

2. ELECTRICAL SPECIFICATION

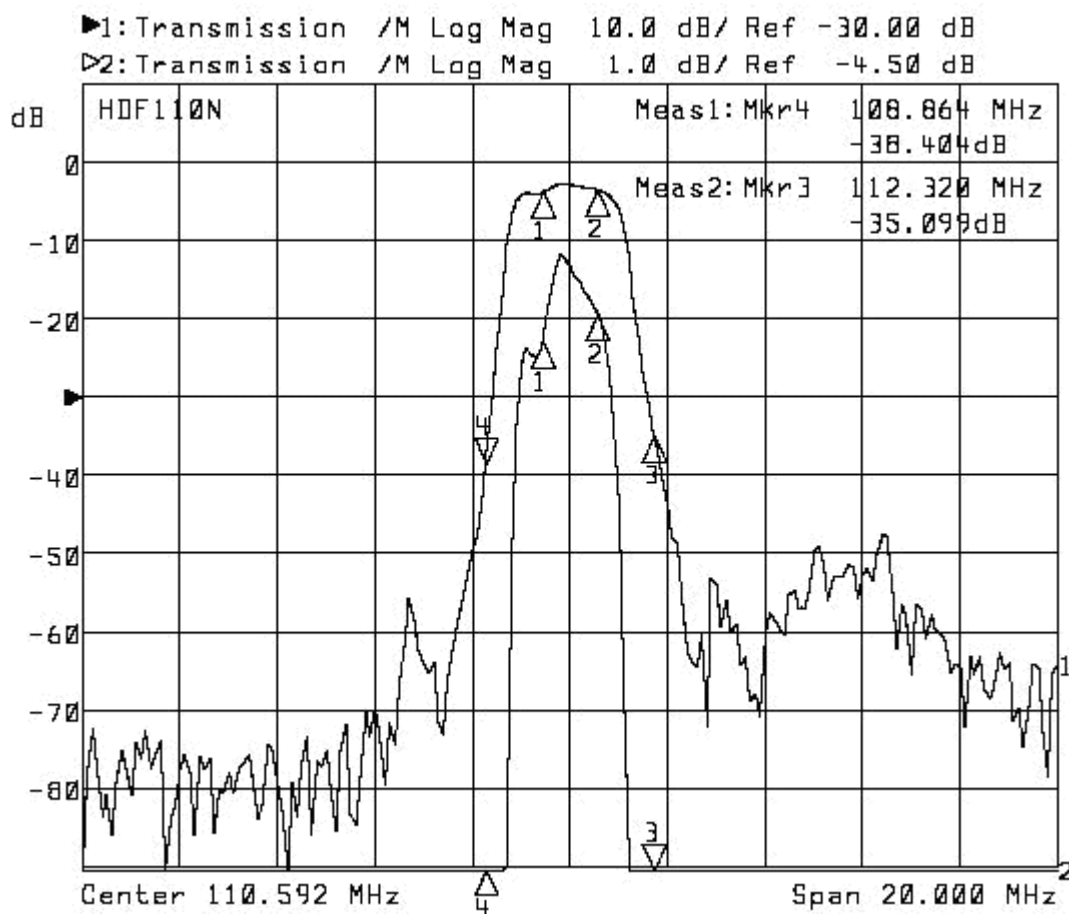
DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-20°C to +55°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

Electronic Characteristics

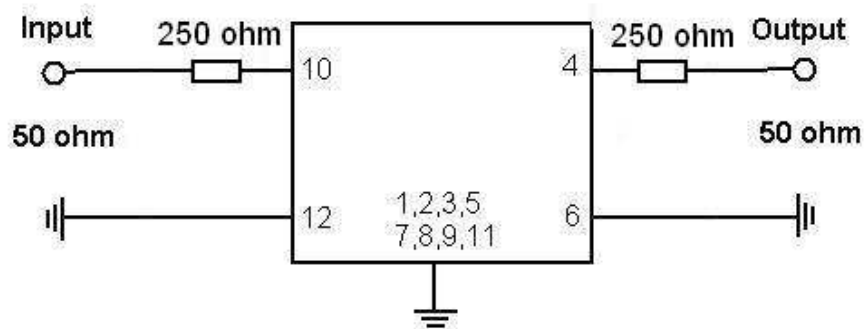
型号 Part Number	HDF110N
中心频率(fo)(MHz) Nominal Center Frequency	110.592
3dB 带宽 Bandwidth(from fo)(KHz)	+/-576min
阻带衰耗 Stop Band Attenuation (from peak level)(dB) 1)fo-3×1.728MHz 2)fo-2×1.728MHz 3)fo+/-1.728MHz 4)fo+2×1.728MHz 5)fo+3×1.728MHz	50min 45min 30min 40min 40min
插入损耗(dB) Insertion Loss(at minimum loss point)	4.5max

群延时波动($f_0 \pm 576\text{KHz}$)($\mu\text{sce.}$) Group Delay Deviation	0.7
输入/输出阻抗 Input/output Impedance	$300\Omega//1.2\mu\text{H}$

Typical frequency response



3. DIMENSION



Subject the device terminals into the solder bath at 245°C $\pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in table 1.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in table 1.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in table 1.

5-8 Lead fatigue

5-8-1 Pulling test

Weight along with the direction of lead without an shock 1kg. The device shall satisfy all the initial Characteristics.

5-8-2 Bending test

Lead shall be subject to withstand against 90°C bending with 450g weight in the direction of thickness. This operation shall be done toward both direction. The device shall show no evidence of damage and shall satisfy all the initial electrical characteristics.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

7. Packing

7.1 Dimensions

(1) Carrier Tape: Figure 1

(2) Reel: Figure 2

(3) The product shall be packed properly not to be damaged during transportation and storage.

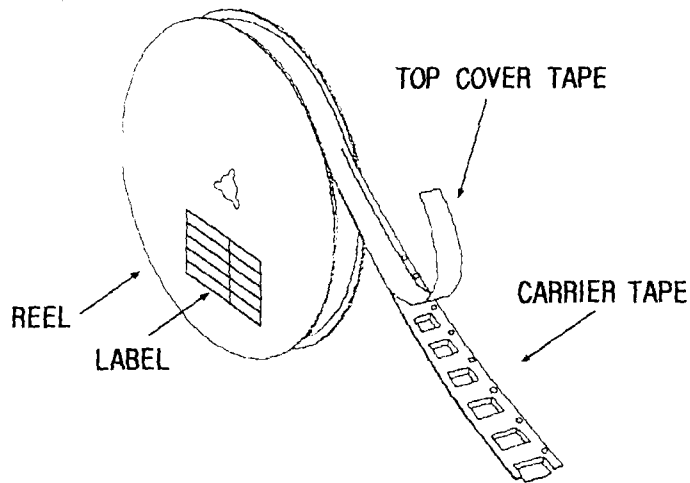
7.2 Reeling Quantity

1000 pcs/reel 7"

3000 pcs/reel 13"

7.3 Taping Structure

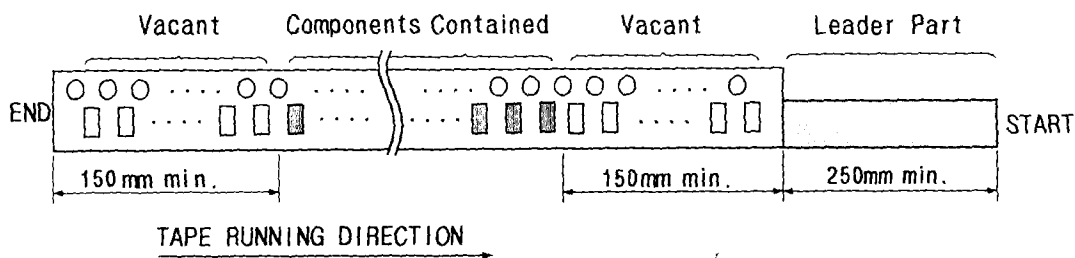
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



8. TAPE SPECIFICATIONS

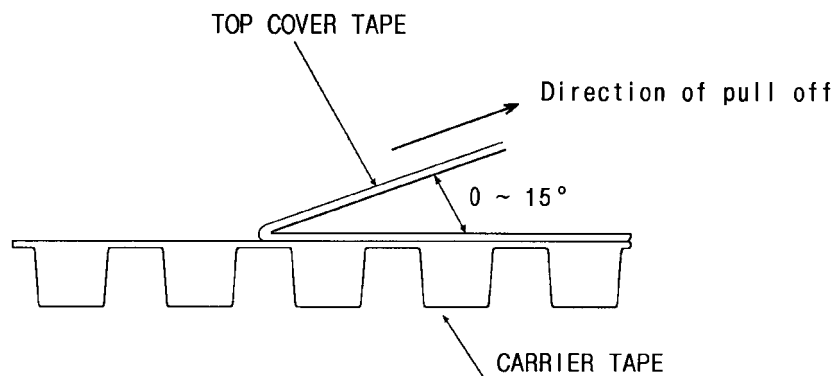
8.1 Tensile Strength of Carrier Tape: 4.4N/mm width

8.2 Top Cover Tape Adhesion (See the below figure)

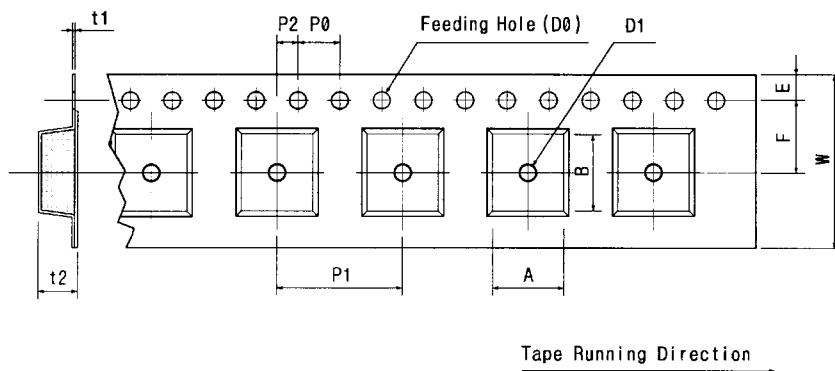
(1) pull off angle: 0~15°

(2) speed: 300mm/min.

(3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

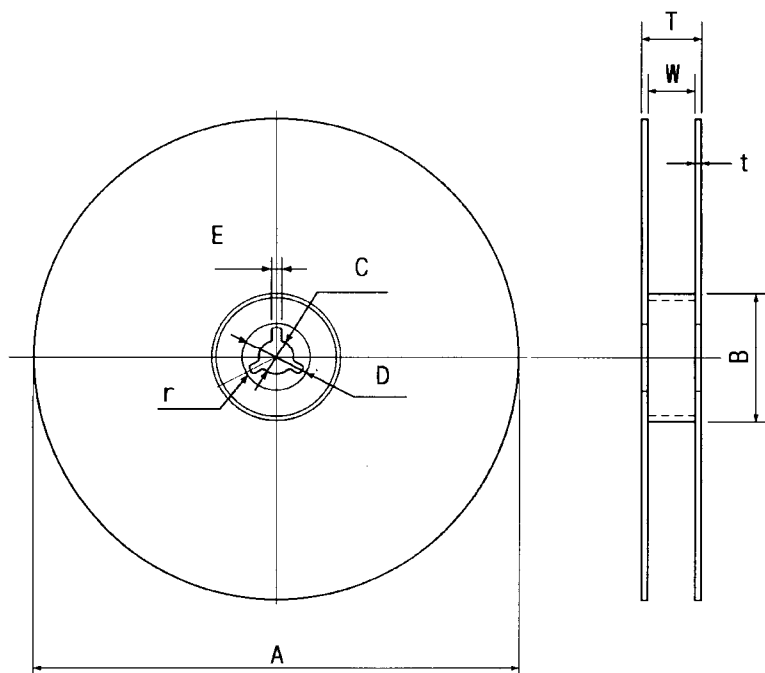


[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.00 ±0.30	7.50 ±0.10	1.75 ±0.10	4.00 ±0.10	8.00 ±0.10	2.00 ±0.10	Ø1.50	Ø1.5 ±0.25	0.25 ±0.05	2.20 ±0.10	5.30 ±0.10	7.30 ±0.10

[Figure 2]

[Unit:mm]



A	B	C	D	E	W	t	r
Ø330	Ø100	Ø13	Ø21	2	16.8	3	1.0
±1.0	±0.5	±0.5	±0.8	±0.5	±0.3	max.	max.

9. CAUTION

- 9-1. This is an electrostatic sensitive device. Please avoid static voltage during operation and storage.
- 9-2. Sudden change of temperature shall be avoided ,deterioration If the characteristics can occur.
- 9-3. Ultrasonic vibration may cause deterioration and destruction of the components Please avoid ultrasonic cleaning.